



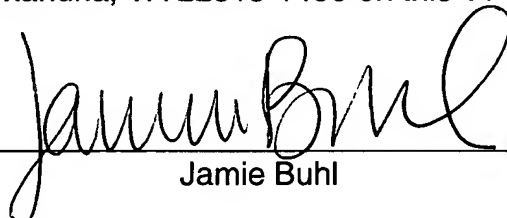
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Enzo CAROLLO  
Title: HIGH-DENSITY PLASMA PROCESS FOR DEPOSITING A  
LAYER OF SILICON NITRIDE  
Serial Number: 10/686,556  
Filing Date: October 14, 2003  
Examiner/Unit: Timothy Howard Meeks/1762  
Attorney Docket No.: 2110-81-3

**Certificate of Mailing**

I hereby certify that this paper is being deposited with the United States Postal Service as First Class Mail and is addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 11<sup>th</sup> day of April, 2005.

  
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Jamie Buhl

**AMENDMENT AND RESPONSE UNDER 37 CFR §1.111**

April 11, 2005

TO THE COMMISSIONER FOR PATENTS  
P.O. Box 1450  
ALEXANDRIA, VA 22313-1450:

Receipt of an Office Action mailed January 11, 2005 is acknowledged. Please amend the above-referenced patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 4 of this paper.